

# Investigations Regarding Thin Films and Coatings Used in Microelectronic Devices

**Michel IGNAT<sup>1</sup>, A.C. SEGUINEAU<sup>2</sup>, A. CHOUAF<sup>3</sup>, X. LAFONTAN<sup>2</sup>, J.-M. DESMARRES<sup>4</sup>**

<sup>1</sup> ENSEEG INPG, Université Joseph Fourier, Saint-Martin-d'Hères, France; <sup>2</sup> Nova MEMS, Ramonville, France; <sup>3</sup> Ecole Nationale Supérieure d'Electricité et Mécanique, Casablanca, Maroc; <sup>4</sup> CNES, DCT/AQ/LE, Toulouse, France  
michel.ignat@inpg.fr

## Abstract

Micro-tensile experiments are useful to determine the mechanical response of thin films and coatings used in most microelectronic devices. Tensile tests were performed on specimens consisting in electroplated thin copper films and structures, deposited on polyimide type substrates. Two aspects of reliability issues have been addressed on this sort of film on substrate systems: -one corresponds to the degradation of a film on a substrate, when submitted to several cyclic mechanical solicitations; the other one, -corresponds to the effect produced by geometrical and material discontinuities at the interfaces, on the local stress fields. In our case at the contours of the copper structures in contact with their polyimide substrate.

**Keywords:** Reliability, Tensile tests, Thin films, Coatings, Microelectronic devices.

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